



Microspherical Silica for Low Dk and Low Df Dielectric Performance

AGC has developed two types of silica fillers providing superior low Dk and low Df performance for films, molded plastics and PCB boards.

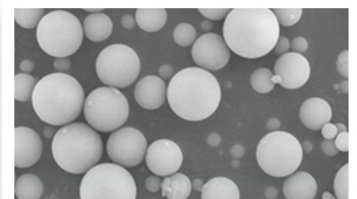
With the continual need for smaller and thinner electronics, superior transmission performance is needed at high frequencies. RESIFA silica is ideal in providing low Dk and low Df performance because they help minimize electric power loss and signal loss.

Advantages of RESIFA silica

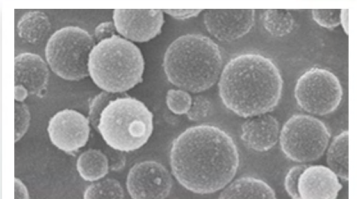
- Low transmission loss
- Stable along a wide temperature range
- Signal stability

Property and Data Information

Property	Units	AGC Hollow Silica HS-200	Low-Df Silica HNP-20B
d50	μm	2	3
dmax	μm	≤10	10
Density	g/cm ³	0.5~0.6	2.2
Dielectric Constant (Dk) @10GHz SPDR	-	1.5~1.6	4.0
Dielectric Tangent (Df) @10GHz SPDR	-	0.001	0.0004~5

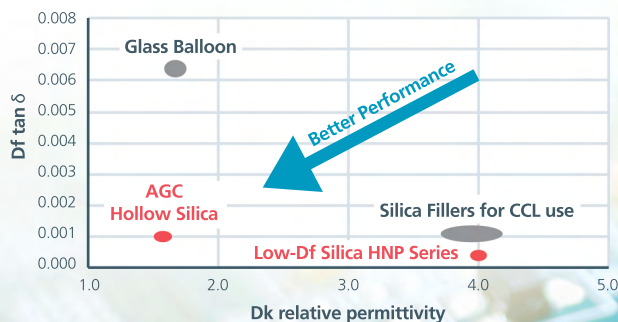


RESIFA HS-200 for Low-Dk



RESIFA HNP-20B for Low-Df

Dielectric Property of Silica Fillers @ 1GHz



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